

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Correspondence and Mail

AF, 2800

Applicant: Frank O'Mahony et al.

Title: LOW LOSS INTERCONNECT STRUCTURE FOR USE IN MICROELECTRONIC CIRCUITS

Docket No.: 884.405US1
Filed: June 27, 2001
Examiner: Ahmed Sefer
Customer No.: 21186



Serial No.: 09/893023
Due Date: October 16, 2003
Group Art Unit: 2826
Confirmation No.: 3406

MS AF

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

- ☒ A return postcard.
- ☒ An Amendment and Response Under 37 CFR 1.116 (10 Pages).
- ☒ Communication Concerning Related Patents (1 pg.).

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
Customer Number 21186

By: David R. Cochran
Atty: David R. Cochran
Reg. No. 46,632

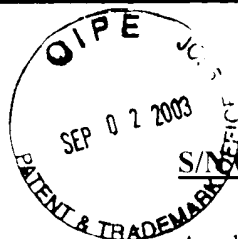
CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 21 day of August, 2003.

KACIA LEE
Name

Kacia Lee
Signature

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
(GENERAL)

Customer Number 21186



S/N 09/893023

PATENTIN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Examiner: Ahmed Sefer

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Docket: 884.405US1

Title: LOW LOSS INTERCONNECT STRUCTURE FOR USE IN
MICROELECTRONIC CIRCUITS

Assignee: Intel Corporation

Customer No.: 21186

COMMUNICATION CONCERNING RELATED PATENTSMail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related patents in the above-identified patent application:

<u>Patent No.</u>	<u>Serial No.</u>	<u>Filing Date</u>	<u>Attorney Docket</u>
6,522,186	09/893,067	June 27, 2001	884.431US1

Respectfully submitted,

FRANK O'MAHONY ET AL.

By Applicants' Representatives,

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By

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CERTIFICATE UNDER 37 CFR 1.8 The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop AF, Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 29 day of August, 2003.

Name

KACIA LEE

Signature

Kacia Lee

EXPEDITED PROCEDURE – EXAMINING GROUP 2826

S/N 09/893023

PATENT

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Applicant: Frank O'Mahony et al.

Examiner: Ahmed Sefer

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Assignee: Intel Corporation

Customer No.: 21186

AMENDMENT & RESPONSE UNDER 37 C.F.R. 1.116

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In response to the final Office Action mailed July 16, 2003, please amend the application as follows: